

Product/Process Change Notice - PCN 22 0216 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Conversion of mold compound from GE100 to G311E

Publication Date: 07-Sep-2022

Effectivity Date: 10-Dec-2022 (the earliest date that a customer could expect to receive changed material)

Revision Description:

Initial Release

Description Of Change:

Change of mold compound from GE100 to G311E.

Reason For Change:

For better mold underfill. G311E has finer filler size compared to GE100.

Impact of the change (positive or negative) on fit, form, function & reliability:

Positive impact to reliability.

Product Identification (this section will describe how to identify the changed material)

This is through date code in product marking. Change will take effect starting WW49 onwards.

Summary of Supporting Information:

Test correlation and validation has been performed per ADI's standard product site to site and/or platform change correlation procedure. See attached Qualification Report.

Supporting Documents

Attachment 1: Type: Qualification Results Summary ADI_PCN_22_0216_Rev_-_LTM8071-G311_PCN.pdf

For questions on this PCN	please send an email to the re	gional contacts below or contact v	your local ADI sales representatives.

Americas: Europe: Japan: Rest of Asia:

PCN_Americas@analog.com PCN_Europe@analog.com PCN_Japan@analog.com PCN_ROA@analog.com

Appendix A - Affected ADI Models					
Added Parts On This Revision - Product Family / Model Number (3)					
LTM8071 / LTM8071EY#PBF	LTM8071 / LTM8071IY	LTM8071 / LTM8071IY#PBF			

Appendix B - Revision History					
Rev	Publish Date	Effectivity Date	Rev Description		
Rev	07-Sep-2022	10-Dec-2022	Initial Release		

Analog Devices, Inc.

Docld:9010 Parent Docld:None Layout Rev:8